Low-Voltage 1.8/2.5/3.3V 16-Bit D-Type Flip-Flop

With 3.6 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The 74VCXH16374 is an advanced performance, non-inverting 16-bit D-type flip-flop. It is designed for very high-speed, very low-power operation in 1.8 V, 2.5 V or 3.3 V systems. The VCXH16374 is byte controlled, with each byte functioning identically, but independently. Each byte has separate Output Enable and Clock Pulse inputs. These control pins can be tied together for full 16-bit operation.

When operating at 2.5 V (or 1.8 V) the part is designed to tolerate voltages it may encounter on either inputs or outputs when interfacing to 3.3 V busses. It is guaranteed to be overvoltage tolerant to 3.6V.

The 74VCXH16374 consists of 16 edge-triggered flip-flops with individual D-type inputs and 3.6 V-tolerant 3-state outputs. The clocks (CPn) and Output Enables (\overline{OEn}) are common to all flip-flops within the respective byte. The flip-flops will store the state of individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the \overline{OE} LOW, the contents of the flip-flops are available at the outputs. When the \overline{OE} is HIGH, the outputs go to the high impedance state. The \overline{OE} input level does not affect the operation of the flip-flops. The data inputs include active bushold circuitry, eliminating the need for external pullup resistors to hold unused or floating inputs at a valid logic state.

Features

- Designed for Low Voltage Operation: $V_{CC} = 1.65 \text{ V} 3.6 \text{ V}$
- 3.6 V Tolerant Inputs and Outputs
- High Speed Operation: 3.0 ns max for 3.0 V to 3.6V

3.9 ns max for 2.3 V to 2.7V

7.8 ns max for 1.65 V to 1.95V

- Static Drive: ±24 mA Drive at 3.0 V
 - ±18 mA Drive at 2.3 V

±6 mA Drive at 1.65 V

- Supports Live Insertion and Withdrawal
- Includes Active Bushold to Hold Unused or Floating Inputs at a Valid Logic State
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0 V^*$
- Near Zero Static Supply Current in All Three Logic States (20 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±250 mA @ 125°C
- ESD Performance: Human Body Model >2000 V Machine Model >200 V
- All Devices in Package TSSOP are Inherently Pb-Free**
- *To ensure the outputs activate in the 3-state condition, the output enable pins should be connected to V_{CC} through a pullup resistor. The value of the resistor is determined by the current sinking capability of the output connected to the \overline{OE} pin.
- **For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



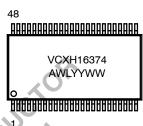
ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM



TSSOP-48 DT SUFFIX CASE 1201



A WI = Assembly Location

WL VV = Wafer Lot = Year

Y M

= Work Week

PIN NAMES

Pins	Function
OEn	Output Enable Inputs
CPn D0-D15	Clock Pulse Inputs Inputs
O0-O15	Outputs

ORDERING INFORMATION

Device	Package	Shipping [†]
74VCXH16374DT	TSSOP (Pb-Free)	39 / Rail
74VCXH16374DTR	TSSOP (Pb-Free)	2500 / Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

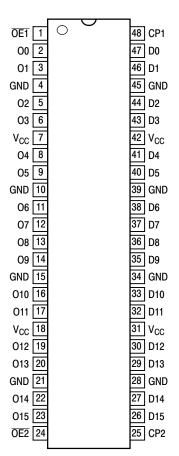


Figure 1. 48-Lead Pinout (Top View)

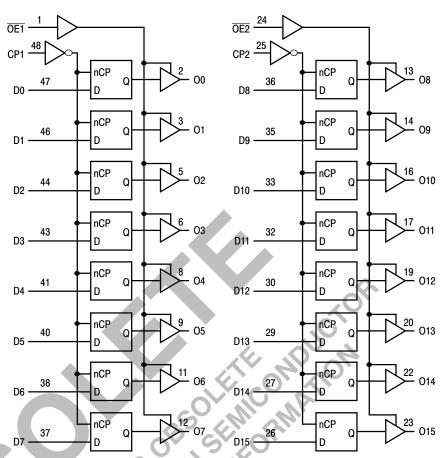


Figure 2. Logic Diagram

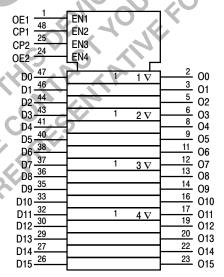


Figure 3. IEC Logic Diagram

TRUTH TABLE

	Inputs		Outputs		Inputs		Outputs
CP1	OE1	D0:7	O0:7	CP2	OE2	D8:15	O8:15
1	L	Н	Н	1	L	Н	Н
1	L	L	L	1	L	L	L
Х	L	Х	00	Х	L	Х	00
Х	Н	X	Z	Х	Н	Х	Z

H = High Voltage Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +4.6	~	V
VI	DC Input Voltage	$-0.5 \le V_{ } \le +4.6$		V
V _O	DC Output Voltage	$-0.5 \le V_0 \le +4.6$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1; Outputs Active	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Io	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter C		Min	Тур	Max	Unit
V _{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.2	3.3 3.3	3.6 3.6	V
VI	Input Voltage		-0.3		3.6	V
V _O	Output Voltage	(Active State) (3-State)	0 0		V _{CC} 3.6	V
I _{OH}	HIGH Level Output Current, V _{CC} = 3.0 V - 3.6 V				-24	mA
I _{OL}	LOW Level Output Current, V _{CC} = 3.0 V - 3.6 V				24	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 2.3 V - 2.7 V				-18	mA
I _{OL}	LOW Level Output Current, V _{CC} = 2.3 V - 2.7 V				18	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 1.65 V - 1.95 V				-6	mA
I _{OL}	LOW Level Output Current, V _{CC} = 1.65 V - 1.95 V				6	mA
T _A	Operating Free-Air Temperature		-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V _{IN} from 0.8 V to 2.0	V, V _{CC} = 3.0 V	0		10	ns/V

L = Low Voltage Level

Z = High Impedance State

[↑] Low-to-High Transition

X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs.

O0 = No Change.

^{1.} I_O absolute maximum rating must be observed.

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°	C to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2)	1.65 V ≤ V _{CC} < 2.3 V	0.65 x V _{CC}		V
		2.3 V ≤ V _{CC} ≤ 2.7 V	1.6		
		2.7 V < V _{CC} ≤ 3.6 V	2.0		
V _{IL}	LOW Level Input Voltage (Note 2)	1.65 V ≤ V _{CC} < 2.3 V		0.35 x V _{CC}	V
		2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	
		2.7 V < V _{CC} ≤ 3.6 V		0.8	
V _{OH}	HIGH Level Output Voltage	1.65 V ≤ V _{CC} ≤ 3.6 V; I _{OH} = −100 μA	V _{CC} - 0.2		V
		V _{CC} = 1.65 V; I _{OH} = -6 mA	1.25		
		V _{CC} = 2.3 V; I _{OH} = -6 mA	2.0		
		V _{CC} = 2.3 V; I _{OH} = -12 mA	1.8		
		V _{CC} = 2.3 V; I _{OH} = -18 mA	1.7	0	
		V _{CC} = 2.7 V; I _{OH} = -12 mA	2.2	.0	
		V _{CC} = 3.0 V; I _{OH} = -18 mA	2.4		
		V _{CC} = 3.0 V; I _{OH} = -24 mA	2.2		
V _{OL}	LOW Level Output Voltage	1.65 V ≤ V_{CC} ≤ 3.6 V; I_{OL} = 100 μ A		0.2	V
		V _{CC} = 1.65 V; I _{OL} = 6 mA		0.3	
		V _{CC} = 2.3 V; I _{OL} = 12 mA	C . C	0.4	
		V _{CC} = 2.3 V; I _{OL} = 18 mA	, elli	0.6	
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	
		$V_{CC} = 3.0 \text{ V; } I_{OL} = 18 \text{ mA}$, O	0.4	
		$V_{CC} = 3.0 \text{ V; } I_{OL} = 24 \text{ mA}$	P	0.55	
I _I	Input Leakage Current	1.65 V ≤ V _{CC} ≤ 3.6 V; 0 V ≤ V _I ≤ 3.6 V		±5.0	μΑ
I _{I(HOLD)}	Minimum Bushold Input Current	$V_{CC} = 3.0 \text{ V}, V_{IN} = 0.8 \text{ V}$	75		μΑ
		$V_{CC} = 3.0 \text{ V}, V_{IN} = 2.0 \text{ V}$	-75		
		$V_{CC} = 2.3 \text{ V}, V_{IN} = 0.7 \text{ V}$	45		
		V _{CC} = 2.3 V, V _{IN} = 1.6 V	-45		
		V _{CC} = 1.65 V, V _{IN} = 0.57 V	25		
		V _{CC} = 1.65 V, V _{IN} = 1.07 V	-25		
I _{I (OD)}	Minimum Bushold Over-Drive	V _{CC} = 3.6 V, (Note 3)	450		μΑ
	Current Needed to Change State	V _{CC} = 3.6 V, (Note 4)	-450		
	PLEASE	V _{CC} = 2.7 V, (Note 3)	300		
		V _{CC} = 2.7 V, (Note 4)	-300		
		V _{CC} = 1.95 V, (Note 3)	200		
	× ·	V _{CC} = 1.95 V, (Note 4)	-200		
l _{OZ}	3-State Output Current	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{O} \le 3.6 \text{ V};$ $\text{V}_{I} = \text{V}_{IH} \text{ or V}_{IL}$		±10	μΑ
I _{OFF}	Power-Off Leakage Current	$V_{CC} = 0 \text{ V}; \text{ V}_{I} \text{ or } \text{V}_{O} = 3.6 \text{ V}$		10	μΑ
I _{CC}	Quiescent Supply Current (Note 5)	1.65 V ≤ V _{CC} ≤ 3.6 V; V _I = GND or V _{CC}		20	μΑ
		1.65 V ≤ V _{CC} ≤ 3.6 V; 3.6 V ≤ V _I , V _O ≤ 3.6 V		±20	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	$2.7 \text{ V} < \text{V}_{CC} \le 3.6 \text{ V}; \text{V}_{IH} = \text{V}_{CC} - 0.6 \text{ V}$		750	μА

^{2.} These values of V_I are used to test DC electrical characteristics only.

An external driver must source at least the specified current to switch from LOW-to-HIGH.
 An external driver must source at least the specified current to switch from HIGH-to-LOW.
 Outputs disabled or 3-state only.

AC CHARACTERISTICS (Note 6; $t_R = t_F = 2.0 \text{ ns}$; $C_L = 30 \text{ pF}$; $R_L = 500 \Omega$)

					$T_A = -40$	0°C to +85°	С		
			V _{CC} = 3.0	V to 3.6 V	V _{CC} = 2.3	V to 2.7 V	V _{CC} = 1.65	V to 1.95 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
f _{max}	Clock Pulse Frequency	1	250		200		100		MHz
t _{PLH} t _{PHL}	Propagation Delay CP-to-On	1	0.8 0.8	3.0 3.0	1.0 1.0	3.9 3.9	1.5 1.5	7.8 7.8	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	4.6 4.6	1.5 1.5	9.2 9.2	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	3.8 3.8	1.5 1.5	6.8 6.8	ns
t _s	Setup Time, High or Low Dn-to-CP	3	1.5		1.5		2.5		ns
t _h	Hold Time, High or Low Dn-to-CP	3	1.0		1.0		1.0		ns
t _w	CP Pulse Width, High	3	1.5		1.5		4.0	\P\	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 7)			0.5 0.5		0.5 0.5	.G	0.75 0.75	ns

AC CHARACTERISTICS ($t_R = t_F = 2.0 \text{ ns}$; $C_L = 50 \text{ pF}$; $R_L = 500 \Omega$)

				T _A = -40°C to +85°	C		
			V _{CC} = 3.0	V to 3.6 V	V _{CC} =	2.7 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
f _{max}	Clock Pulse Frequency	4	150	· ~ ~	150		MHz
t _{PLH} t _{PHL}	Propagation Delay CP-to-On	4	1.0 1.0	4.2 4.2		4.9 4.9	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	5	1.0 1.0	4.8 4.8		5.9 5.9	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	5	1.0 1.0	4.3 4.3		4.7 4.7	ns
toshl toslh	Output-to-Output Skew (Note 8)	CO	.cv	0.5 0.5		0.5 0.5	ns

^{8.} Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toSHL) or LOW-to-HIGH (toSLH); parameter guaranteed by design.

 ^{6.} For C_L = 50 pF, add approximately 300 ps to the AC maximum specification.
 7. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C	
Symbol	Characteristic	Condition	Тур	Unit
V _{OLP}	Dynamic LOW Peak Voltage	$V_{CC} = 1.8 \text{ V}, \ C_L = 30 \text{ pF}, \ V_{IH} = V_{CC}, \ V_{IL} = 0 \text{ V}$	0.25	V
	(Note 9)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.6	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.8	
V _{OLV}	Dynamic LOW Valley Voltage	V_{CC} = 1.8 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.25	V
	(Note 9)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.6	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.8	
V _{OHV}	Dynamic HIGH Valley Voltage	$V_{CC} = 1.8 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	1.5	V
	(Note 10)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	1.9	
		$V_{CC} = 3.3 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	2.2	

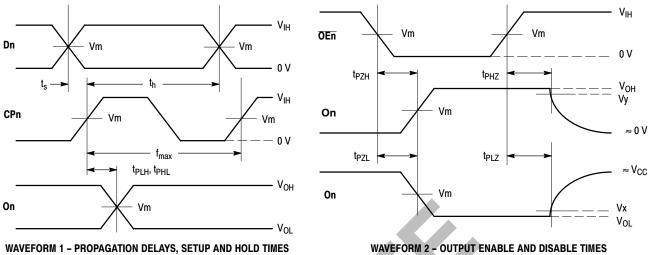
^{9.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
O _{IN}	Input Capacitance	Note 11	6	pF
Соит	Output Capacitance	Note 11	7	pF
C _{PD}	Power Dissipation Capacitance	Note 11, 10 MHz	20	pF
	O PIERSE CO	S DEVICE OUR FOR		

 $[\]overline{11. V_{CC} = 1.8 \text{ V}, 2.5 \text{ V or } 3.3 \text{ V}; V_{I} = 0 \text{ V or } V_{CC}}$

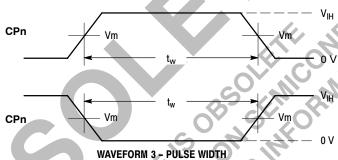
^{10.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the HIGH state.



WAVEFORM 1 - PROPAGATION DELAYS, SETUP AND HOLD TIMES t_R = t_F = 2.0 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

Figure 4. AC Waveforms



WAVEFORM 3 - PULSE WIDTH $t_R = t_F = 2.0$ ns (or fast as required) from 10% to 90%

Figure 5. AC Waveforms

Table 1. AC WAVEFORMS

		V _{CC}	
Symbol	3.3 V ± 0.3 V	2.5 V ± 0.2 V	1.8 V ± 0.15 V
V _{IH}	2.7 V	V _{CC}	V _{CC}
V _m	1.5 V	V _{CC} /2	V _{CC} /2
V _x	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V
V_{y}	V _{OH} – 0.3 V	V _{OH} – 0.15 V	V _{OH} – 0.15 V

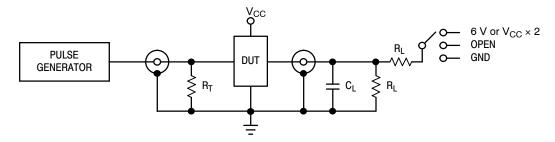
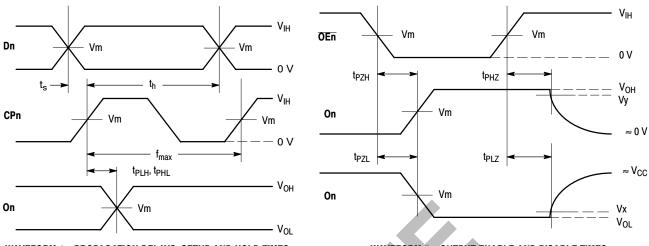


Figure 6. Test Circuit

Table 2. TEST CIRCUIT

TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V at $V_{CC} = 3.3 \pm 0.3 \text{ V};$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2 \text{ V};$ 1.8 \pm 0.15 V
t _{PZH} , t _{PHZ}	GND
C_L = 30 pF or equivalent (Includes jig and R_L = 500 Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50	Open 6 V at V _{CC} = 3.3 ± 0.3 V; V _{CC} × 2 at V _{CC} = 2.5 ± 0.2 V; 1.8 ± 0.15 V GND probe capacitance) Ω)

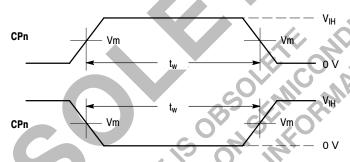


WAVEFORM 4 - PROPAGATION DELAYS, SETUP AND HOLD TIMES

 t_R = t_F = 2.0 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

WAVEFORM 5 - OUTPUT ENABLE AND DISABLE TIMES $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

Figure 7. AC Waveforms



WAVEFORM 6 - PULSE WIDTH t_{R} = t_{F} = 2.0 ns (or fast as required) from 10% to 90%

Figure 8. AC Waveforms

Table 3. AC WAVEFORMS

		V _{cc}		
Syml	ool	3.3 V ± 0.3 V	2.7 V	
V _{II}	1. G	2.7 V	2.7 V	
V _m	< 0	1.5 V	1.5 V	
V _x		V _{OL} + 0.3 V	V _{OL} + 0.3 V	
V _y	Q~ V	V _{OH} – 0.3 V	V _{OH} – 0.3 V	

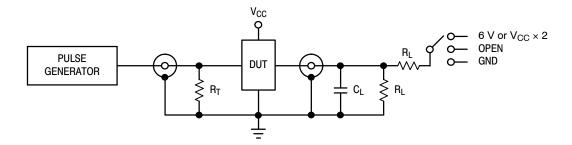


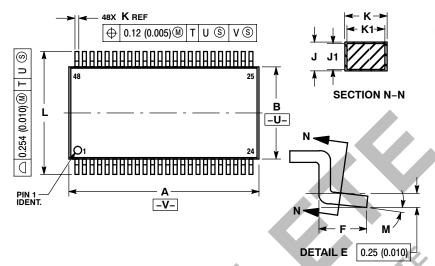
Figure 9. Test Circuit

Table 4. TEST CIRCUIT

TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V at V_{CC} = 3.3 ± 0.3 V; V_{CC} × 2 at V_{CC} = 2.5 ± 0.2 V; 1.8 ± 0.15 V
t _{PZH} , t _{PHZ}	GND
$C_L=50~pF$ or equivalent (Includes jig and $R_L=500~\Omega$ or equivalent $R_T=Z_{OUT}$ of pulse generator (typically 50 s	Open $6 \text{ V at V}_{CC} = 3.3 \pm 0.3 \text{ V};$ $V_{CC} \times 2 \text{ at V}_{CC} = 2.5 \pm 0.2 \text{ V}; 1.8 \pm 0.15 \text{ V}$ GND probe capacitance) $\Omega)$

PACKAGE DIMENSIONS

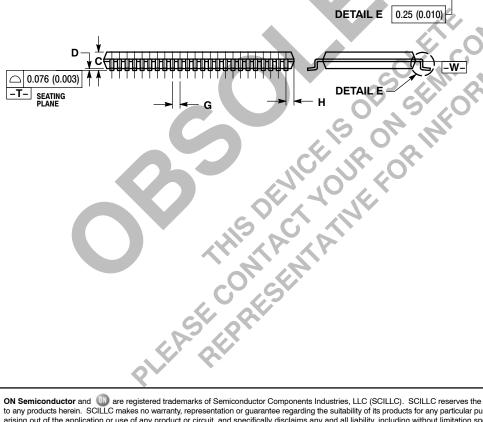
TSSOP DT SUFFIX CASE 1201-01 ISSUE A



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE
- DIMENSIONS A AND B DO NOT INCLUDE MOID FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION K DOES NOT INCLUDE DAMBAR
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- REFERENCE ONLY.
 6. DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	12.40	12.60	0.488	0.496
В	6.00	6.20	0.236	0.244
С		1.10		0.043
D	0.05	0.15	0.002	0.006
	0.50	0.75	0.020	0.030
G	0.50 BSC		0.0197 BSC	
Ξ	0.37	d	0.015	
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.17	0.27	0.007	0.011
K1	0.17	0.23	0.007	0.009
L	7.95	8.25	0.313	0.325
3	0 °	8 0	0 °	8 °



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